

#2 3-2-01

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**priority** Application Serial No. .... 09/389,844  
**priority** Filing Date .... September 2, 1999  
Inventor ..... Salman Akram  
Assignee ..... Micron Technology, Inc.  
**priority** Group Art Unit ..... 2826  
**priority** Examiner ..... F. Abraham  
Attorney's Docket No. .... MI22-1572  
Title: Methods of Forming Board-On-Chip Packages (as amended)

jc872 U.S. PTO  
09/756971



**INFORMATION DISCLOSURE STATEMENT**

References -- See Attached Form PTO-1449

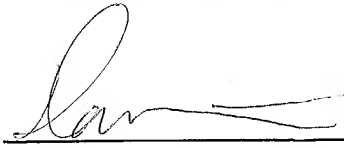
In compliance with 37 C.F.R. §§1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a divisional of co-pending application Serial No. 09/389,844 filed September 2, 1999. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. §1.98(d) and MPEP §609(2). No admission is made regarding whether all the submitted references are prior art.

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: 1/9/2001

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